



Material Content Data Sheet



Sales Product Name		IPB50N10S3L-16		Issued		1. August 2018		
MA#		MA001230908						
Package		PG-TO263-3-2		Weight*		1559.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.497	0.29	0.29	2883	2883
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194913	195167
	non noble metal	aluminium	7429-90-5	5.686	0.36	0.36	3645	3645
wire	non noble metal	aluminium	7429-90-5	5.686	0.36	0.36	3645	3645
encapsulation	organic material	carbon black	1333-86-4	10.244	0.66		6567	
	plastics	epoxy resin	-	112.679	7.22		72239	
	inorganic material	silicondioxide	60676-86-0	559.979	35.89	43.77	359005	437811
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6191	6191
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.081	0.01		52	
	noble metal	silver	7440-22-4	0.101	0.01		65	
	non noble metal	lead	7439-92-1	3.854	0.25	0.27	2471	2588
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.11	35.16	351111	351568
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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